

Specification of Automotive MLCC



• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C151JB81PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 150 pF, 50V, ±5%, C0G, 0603

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>151</u> <u>J</u> <u>B</u> <u>8</u> <u>1</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor				
2	Size	0603 (inch code)	L: 1	.6 ± 0.1 mm	W: 0.8 ± 0.1	mm
3	Dielectric	COG	8	Inner electrode	Ni	
4	Capacitance	150 pF		Termination	Cu	
(5)	Capacitance	±5 %		Plating	Sn 100%	(Pb Free)
	tolerance		9	Product	Automotive	
6	Rated Voltage	50 V	10	Grade code	Standard	
7	Thickness	0.8 ± 0.1 mm	11	Packaging	Cardboard Typ	e, 7" reel(4,000ea)

B. Reliability Test and Judgement condition

	Performance	Test condition	
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150℃	
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion	
	within ±2.5% or ±0.25pF whichever is larger		
	Q: 1000 min		
	IR : More than 10,000 $\mathrm{M}\Omega$ or 500 $\mathrm{M}\Omega imes \mu \mathrm{F}$		
	Whichever is Smaller		
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles	
	Capacitance Change :	Measurement at 24±2hrs after test conclusion	
	within ±2.5% or ±0.25pF whichever is larger	1 cycle condition :	
	Q: 1000 min	-55+0/-3 °C (15±3min) -> Room Temp(1min.)	
	IR : More than 10,000 $\mathrm{M}\Omega$ or 500 $\mathrm{M}\Omega imes \mu \mathrm{F}$	-> 125+3/-0°C (15±3min) -> Room Temp(1min.)	
	Whichever is Smaller		
Destructive Physical No Defects or abnormalities		Per EIA 469	
Analysis			
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle	
	Capacitance Change :	Heat (25~65℃) and humidity (80~98%), Unpowered	
	within ±2.5% or ±0.25pF whichever is larger	measurement at 24±2hrs after test conclusion	
	Q: 350 min		
	IR : More than 10,000MΩ or 500MΩ×μF		
	Whichever is Smaller		
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 ℃/85%RH, Rated Voltate and 1.3~1.5V,	
	Capacitance Change :	Add 100kohm resistor	
	within ±2.5% or ±0.25pF whichever is larger	Measurement at 24±2hrs after test conclusion	
	Q: 200 min	The charge/discharge current is less than 50mA.	
	IR : More than 500MΩ or 25MΩ×μF		
	Whichever is Smaller		
High Temperature Appearance : No abnormal exterior appearance		1000hrs @ TA=125℃, 200% Rated Voltage,	
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion	
	within ±3.0% or ±0.3pF whichever is larger	The charge/discharge current is less than 50mA.	
	Q: 350 min		
	IR : More than 10,000№ or 500№×μF		
	Whichever is Smaller		

	Performance	Test condition			
External Visual	No abnormal exterior appearance	Visual inspection			
Physical Dimensions	Within the specified dimensions	Using The calipers			
Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.		Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks) Peakvalue Duration Wave Velocity 1,500G 0.5ms Half sine 4.7m/sec.			
Vibration	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	5g's for 20min., 12cycles each of 3 orientations, Use 8"x5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2000Hz.			
Resistance to Solder Heat	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	Solder pot : 260±5°C, 10±1sec.			
Thermal Shock	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	-55℃/+125℃. Note: Number of cycles required-300, Maximum transfer time-20 sec, Dwell time-15min. Air-Air			
ESD	Appearance : No abnormal exterior appearance Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.	AEC-Q200-002			
Solderability	95% of the terminations is to be soldered evenly and continuously	 a) Preheat at 155°C for 4 hours, Immerse in solder for 5s at 245±5°C b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5°C c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5°C solder: a solution ethanol and rosin 			
Electrical Characterization	Capacitance: Within specified tolerance Q: 1000 max. IR(25℃): More than 100,000MΩ or 1,000MΩ×μF IR(125℃): More than10,000MΩ or 100MΩ×μF Whichever is Smaller Dielectric Strength	The Capacitance /Q should be measured at 25°C, 1\mu±10%, 0.5~5Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25°C, @125°C for 60~120 sec. Dielectric Strength: 250% of the rated voltage for 1~5 seconds			
Board Flex	Appearance: No abnormal exterior appearance Capacitance Change: within ±5.0% or ±0.5pF whichever is larger	Bending to the limit (3mm) for 5 seconds			
Terminal Strength(SMD)	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger	10N, for 60±1 sec.			
Beam Load	Destruction value should not be exceed Chip Length < 2.5mm a) Chip Thickness > 0.5mm : 20N b) Chip Thickness ≤ 0.5mm : 8N	Beam speed 0.5±0.05mm/sec			
Temperature Characteristics	C0G (From -55 °C to 125 °C, Capacitance change should be within ±30PPM/ °C)				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\!\!\!\mathrm{C}$, 10sec. Max)

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.